

FORM PTO-1449 U.S. Department of Commerce Patent and Trademark Office LIST OF DOCUMENTS CITED BY APPLICANT (Use several sheets if necessary)				Attorney Docket Number 9180-29		Serial No. To Be Assigned	
				Applicants: Krishna K. Nair et al;			
				Filing Date: Concurrently Herewith		Group	
U. S. PATENT DOCUMENTS							
Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date if Appropriate
FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Country	Class	Subclass	Translation Yes No
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
DM	1.	W.J. Choi et al; <i>Electromigration of Flip Chip Solder Bump on Cu/Ni(V) Al Thin Film Under Bump Metallization</i> ; 2002 Electronic Components and Technology Conference; pp 1201-1205.					
DM	2.	K. Zeng et al; <i>Six cases of reliability study of Pb-free solder joints in electronic packaging technology</i> , Reports: A Review Journal; Materials Science and Engineering R 38 (2002) pp 55-105.					

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